

## Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

## Product Summary

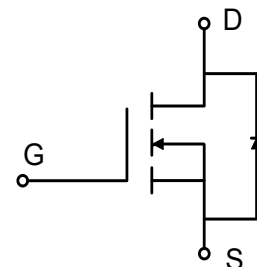
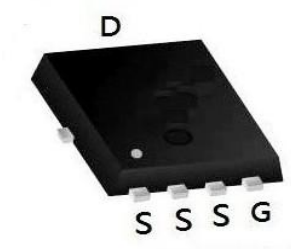


BVDSS	RDSON	ID
150V	9.5mΩ	100A

## Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

## PDFN5060-8L Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	100	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	47	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	292	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	204.8	mJ
$I_{AS}$	Avalanche Current	32	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	178.6	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	52	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	0.7	$^\circ\text{C/W}$

## N-Ch 150V Fast Switching MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=250\mu A$	150	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	---	---	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V$ , $I_D=17A$	---	9.5	11.5	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu A$	2	3	4	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	$mV/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=150V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=150V$ , $V_{GS}=0V$ , $T_J=100^\circ\text{C}$	---	---	100	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=10V$ , $I_D=17A$	---	69	---	S
$R_g$	Gate Resistance	$V_{DS}=0V$ , $V_{GS}=0V$ , $f=1\text{MHz}$	---	3.2	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{DS}=75V$ , $V_{GS}=10V$ , $I_D=17A$	---	45	---	nC
$Q_{gs}$	Gate-Source Charge		---	15	---	
$Q_{gd}$	Gate-Drain Charge		---	8.5	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{GS}=10V$ , $V_{DD}=75V$ , $R_G=3\Omega$ , $I_D=17A$	---	16	---	ns
$T_r$	Rise Time		---	12	---	
$T_{d(off)}$	Turn-Off Delay Time		---	30	---	
$T_f$	Fall Time		---	18	---	
$C_{iss}$	Input Capacitance	$V_{DS}=75V$ , $V_{GS}=0V$ , $f=1\text{MHz}$	---	3310	---	pF
$C_{oss}$	Output Capacitance		---	268	---	
$C_{rss}$	Reverse Transfer Capacitance		---	9.4	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V$ , Force Current	---	---	100	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V$ , $I_S=17A$ , $T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=17A$ , $di/dt=100A/\mu s$ , $T_J=25^\circ\text{C}$	---	76	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	182	---	nC

## Notes:

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ\text{C}$
2. The EAS data shows Max. rating . The test condition is  $V_{DD}=50V$ ,  $V_{GS}=10V$ ,  $L=0.4\text{mH}$ ,  $I_{AS}=32A$ .
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

### Typical Characteristics

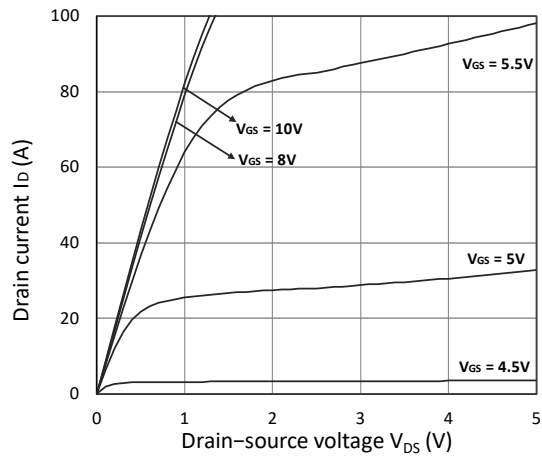


Figure 1. Output Characteristics

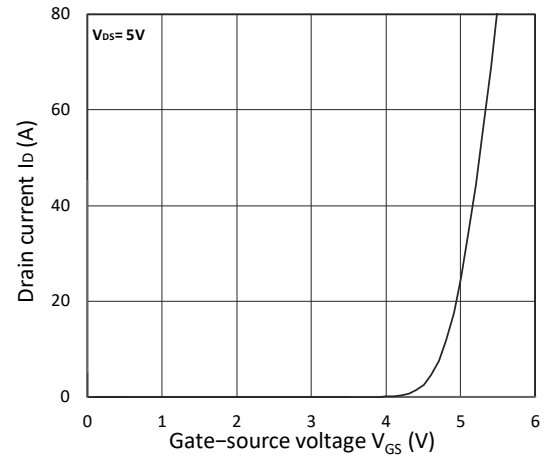


Figure 2. Transfer Characteristics

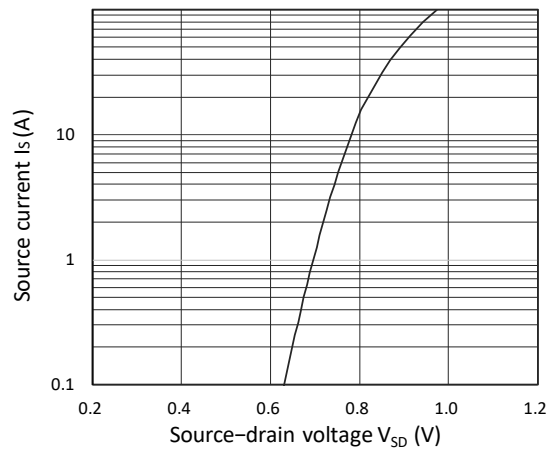


Figure 3. Forward Characteristics of Reverse

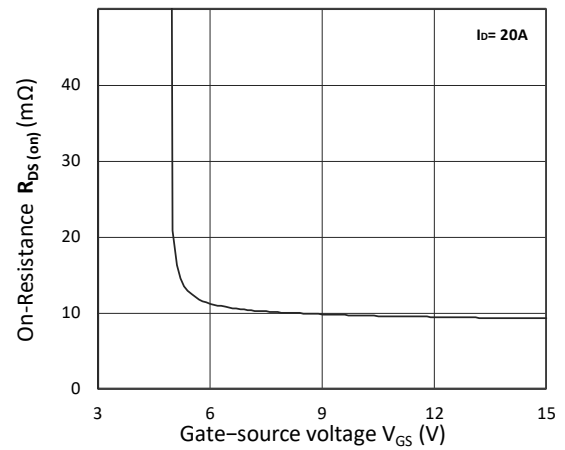


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

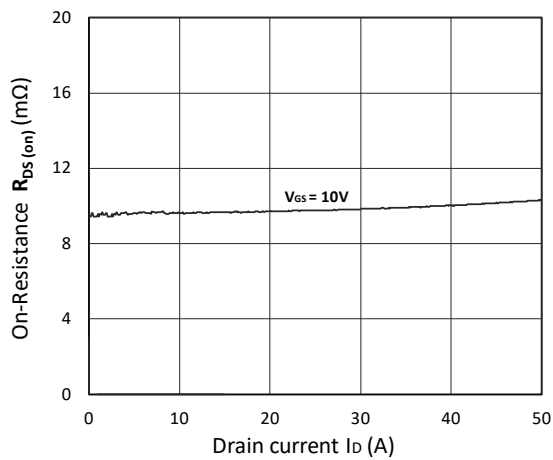


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

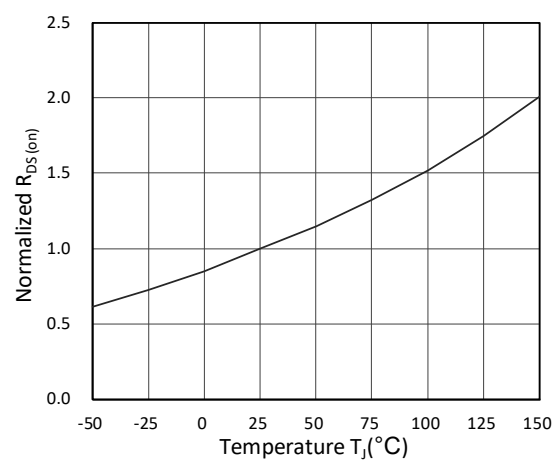


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

## N-Ch 150V Fast Switching MOSFETs

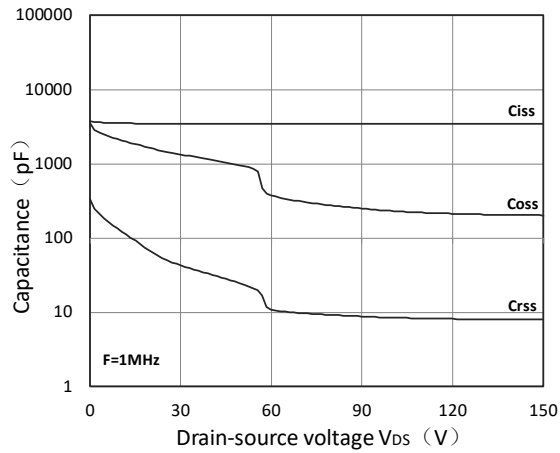


Figure 7. Capacitance Characteristics

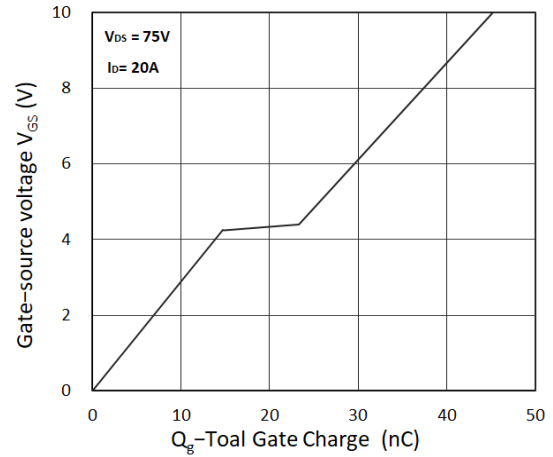


Figure 8. Gate Charge Characteristics

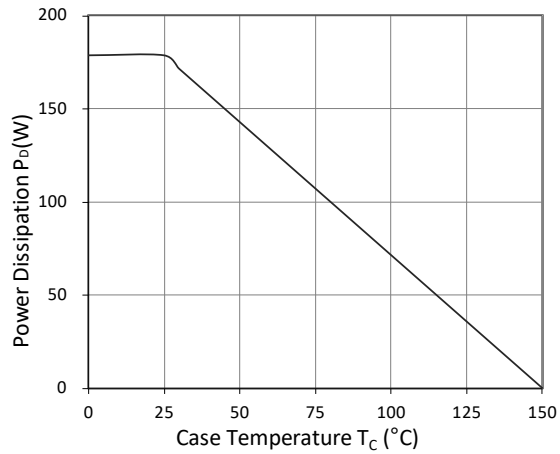


Figure 9. Power Dissipation

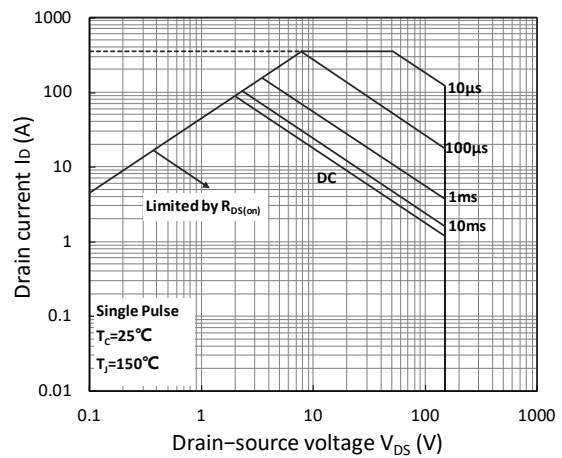


Figure10. Safe Operating Area

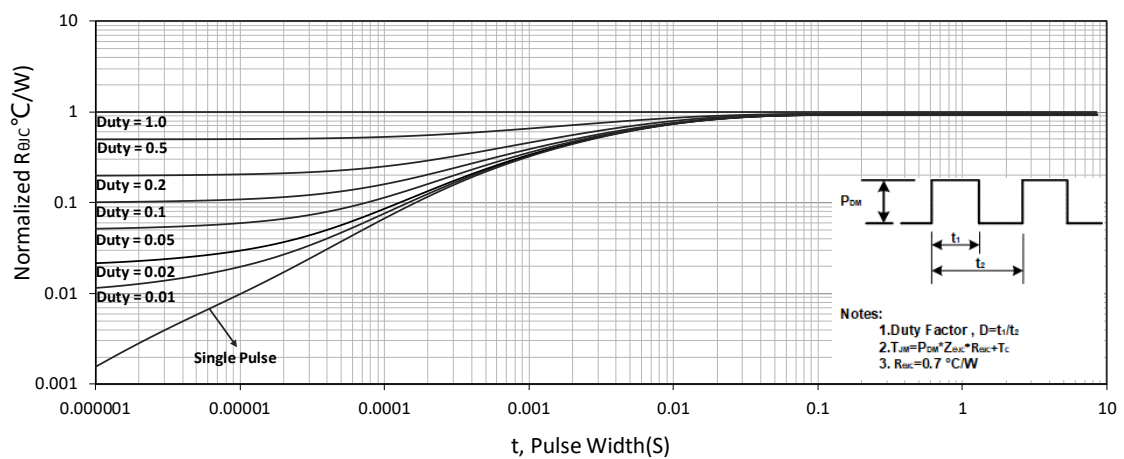


Figure 11. Normalized Maximum Transient Thermal Impedance

### Test Circuit

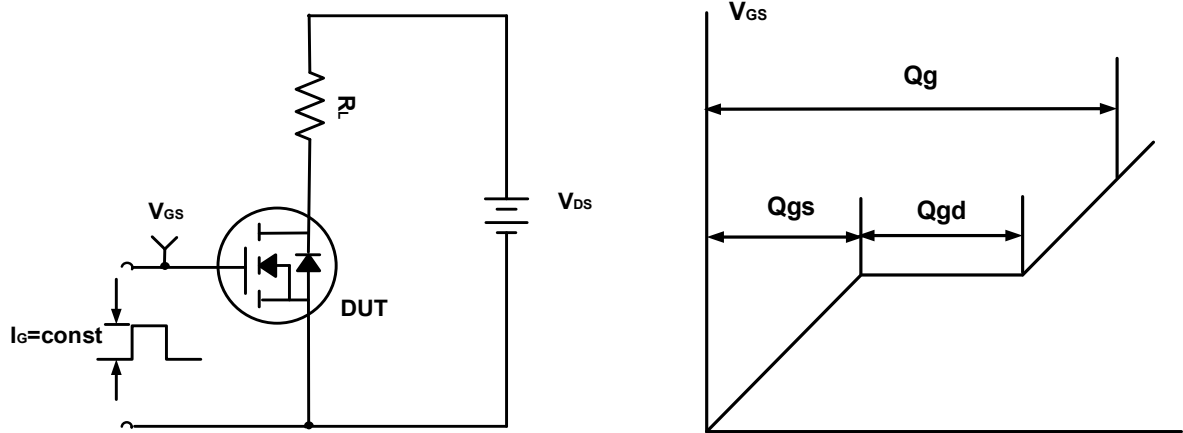


Figure A. Gate Charge Test Circuit & Waveforms

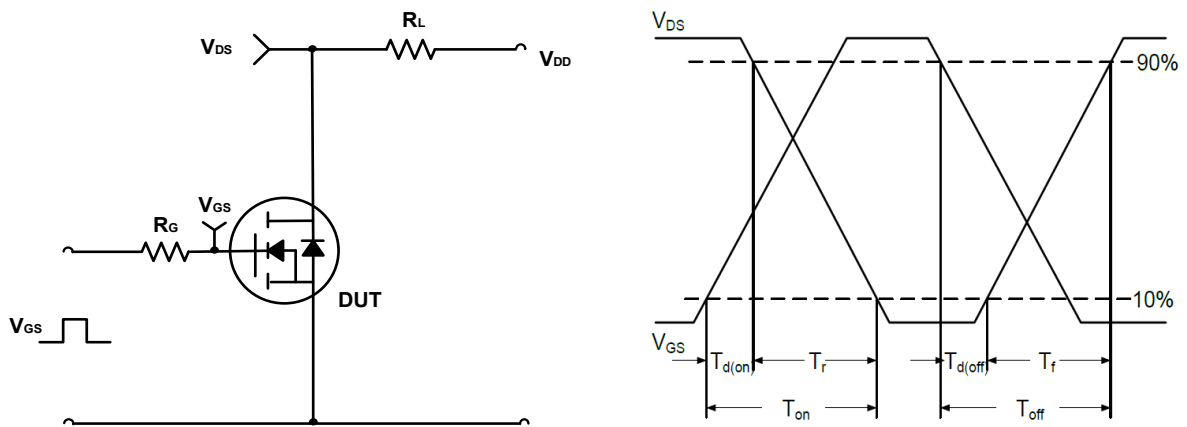


Figure B. Switching Test Circuit & Waveforms

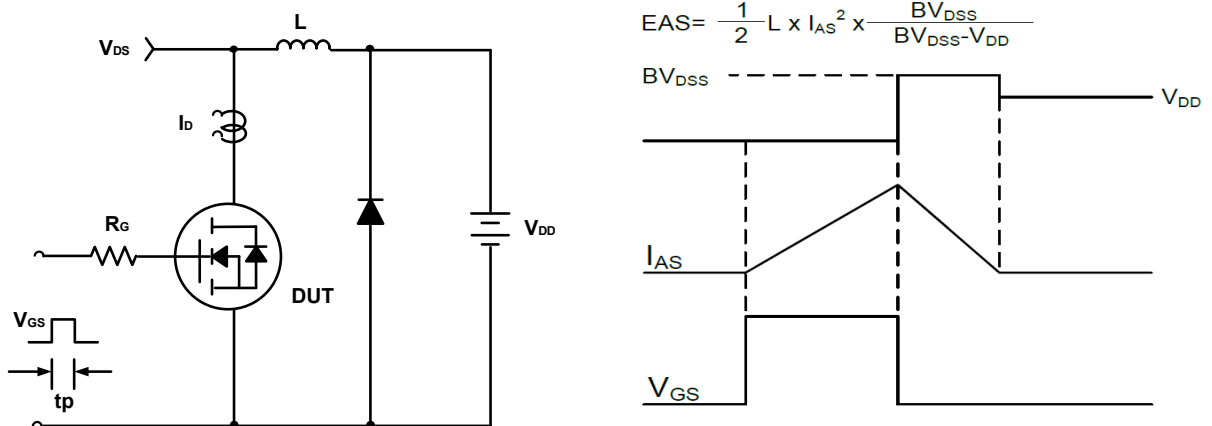
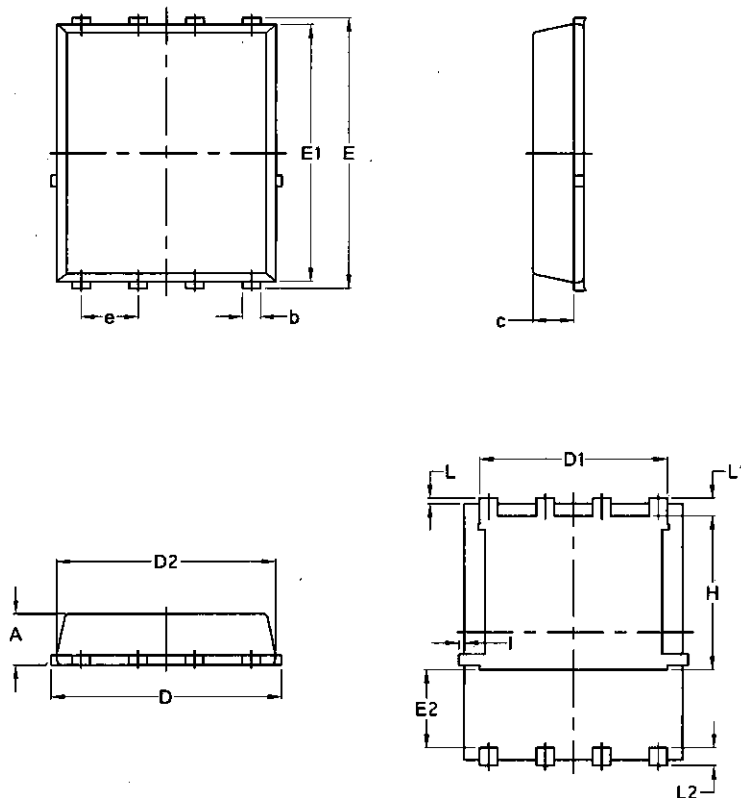


Figure C. Unclamped Inductive Switching Circuit & Waveforms

### Package Mechanical Data-PDFN5060-8L -Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070